

Am29F010 Known Good Die

1 Megabit (128 K x 8-Bit)

CMOS 5.0 Volt-only, Uniform Sector Flash Memory—Die Revision 1

DISTINCTIVE CHARACTERISTICS

■ Single power supply operation

- 5.0 V \pm 10% for read, erase, and program operations
- Simplifies system-level power requirements

■ High performance

- 90 or 120 ns maximum access time

■ Low power consumption

- 30 mA max active read current
- 50 mA max program/erase current
- <25 μ A typical standby current

■ Flexible sector architecture

- Eight uniform sectors
- Any combination of sectors can be erased
- Supports full chip erase

■ Sector protection

- Hardware-based feature that disables/re-enables program and erase operations in any combination of sectors
- Sector protection/unprotection can be implemented using standard PROM programming equipment

■ Embedded Algorithms

- Embedded Erase algorithm automatically pre-programs and erases the chip or any combination of designated sector
- Embedded Program algorithm automatically programs and verifies data at specified address

■ Minimum 100,000 program/erase cycles guaranteed

■ Compatible with JEDEC standards

- Pinout and software compatible with single-power-supply flash
- Superior inadvertent write protection

■ Data Polling and Toggle Bits

- Provides a software method of detecting program or erase cycle completion

■ Tested to datasheet specifications at temperature

■ Quality and reliability levels equivalent to standard packaged components

GENERAL DESCRIPTION

The Am29F010 in Known Good Die (KGD) form is a 1 Mbit, 5.0 Volt-only Flash memory. AMD defines KGD as standard product in die form, tested for functionality and speed. AMD KGD products have the same reliability and quality as AMD products in packaged form.

Am29F010 Features

The Am29F010 device is organized as eight uniform sectors of 16 Kbytes each for flexible erase capability. This device is designed to be programmed in-system with the standard system 5.0 Volt V_{CC} supply. A power supply providing 12.0 Volt V_{PP} is not required for program or erase operations.

The Am29F010 in KGD form offers access times of 90 ns and 120 ns, allowing high speed microprocessors to operate without wait states. To eliminate bus contention the device has separate chip enable (CE#), write enable (WE#) and output enable (OE) controls.

The device requires only a **single 5.0 volt power supply** for both read and write functions. Internally generated and regulated voltages are provided for the program and erase operations.

The device is entirely command set compatible with the **JEDEC single-power-supply Flash standard**. Commands are written to the command register using standard microprocessor write timings. Register contents serve as input to an internal state machine that controls the erase and programming circuitry. Write cycles also internally latch addresses and data needed for the programming and erase operations. Reading data out of the device is similar to reading from other Flash or EPROM devices.

Device programming occurs by executing the program command sequence. This invokes the **Embedded**

Program algorithm—an internal algorithm that automatically times the program pulse widths and verifies proper cell margin.

Device erasure occurs by executing the erase command sequence. This invokes the **Embedded Erase** algorithm—an internal algorithm that automatically preprograms the array (if it is not already programmed) before executing the erase operation. During erase, the device automatically times the erase pulse widths and verifies proper cell margin.

The host system can detect whether a program or erase operation is complete by reading the DQ7 (Data# Polling) and DQ6 (toggle) **status bits**. After a program or erase cycle has been completed, the device is ready to read array data or accept another command.

The **sector erase architecture** allows memory sectors to be erased and reprogrammed without affecting the data contents of other sectors. The device is erased when shipped from the factory.

The **hardware data protection** measures include a low V_{CC} detector automatically inhibits write operations during power transitions. The **hardware sector protection** feature disables both program and erase operations in any combination of the sectors of memory, and is implemented using standard EPROM programmers.

The system can place the device into the **standby mode**. Power consumption is greatly reduced in this mode.

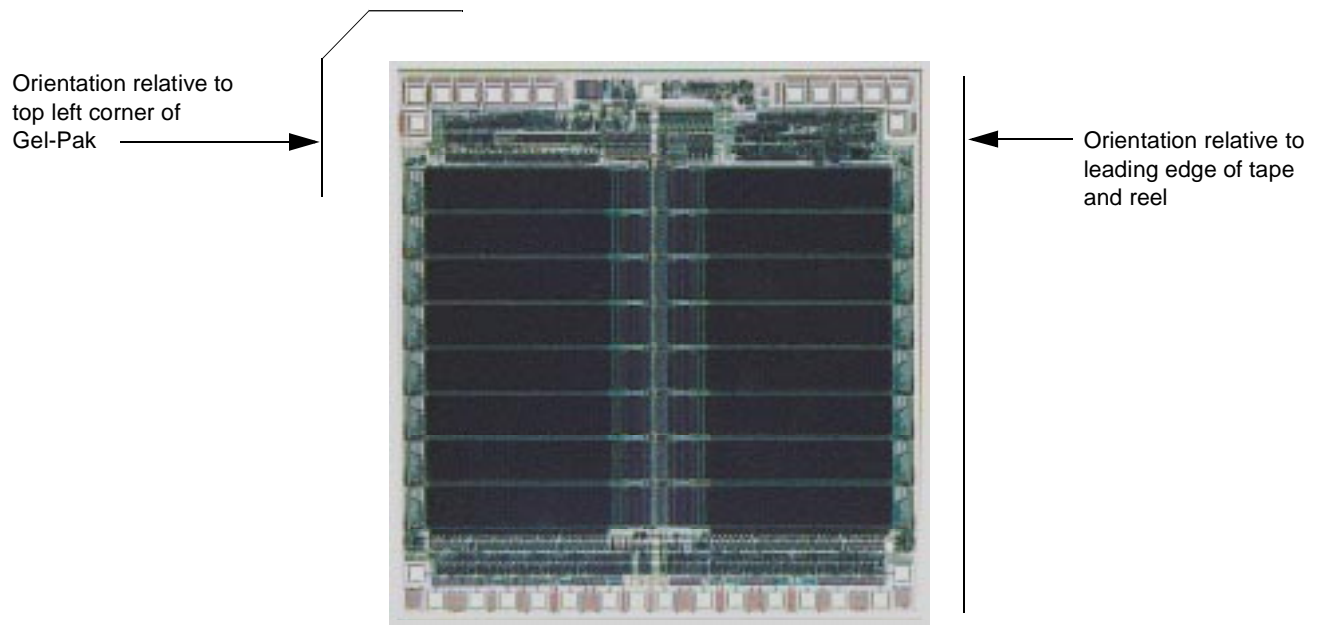
ELECTRICAL SPECIFICATIONS

Refer to the Am29F010 data sheet, publication number 16736, for full electrical specifications for the Am29F010 in KGD form.

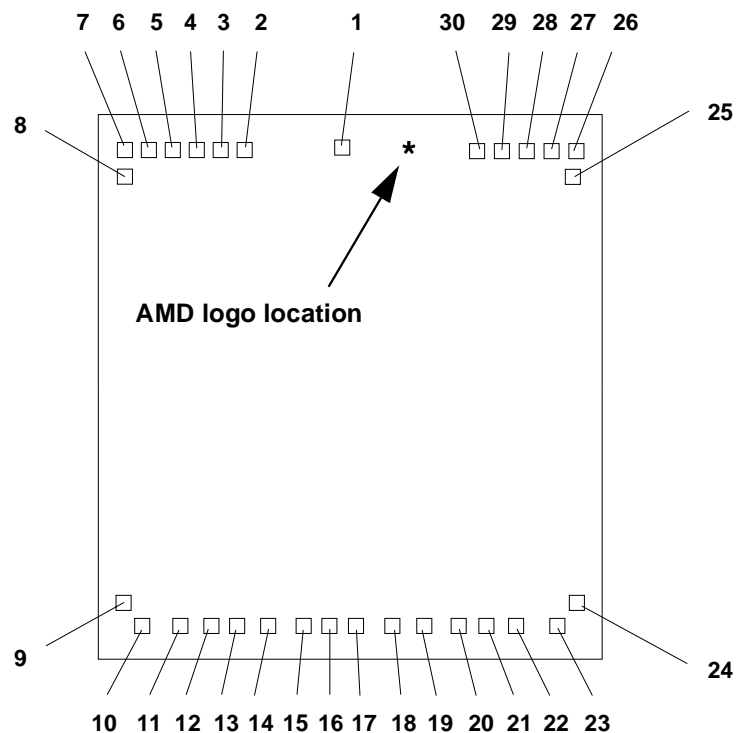
PRODUCT SELECTOR GUIDE

Family Part Number	Am29F010 KGD	
Speed Option ($V_{CC} = 5.0\text{ V} \pm 10\%$)	-90	-120
Max Access Time, t_{ACC} (ns)	90	120
Max CE# Access, t_{CE} (ns)	90	120
Max OE# Access, t_{OE} (ns)	35	50

DIE PHOTOGRAPH



DIE PAD LOCATIONS



PAD DESCRIPTION

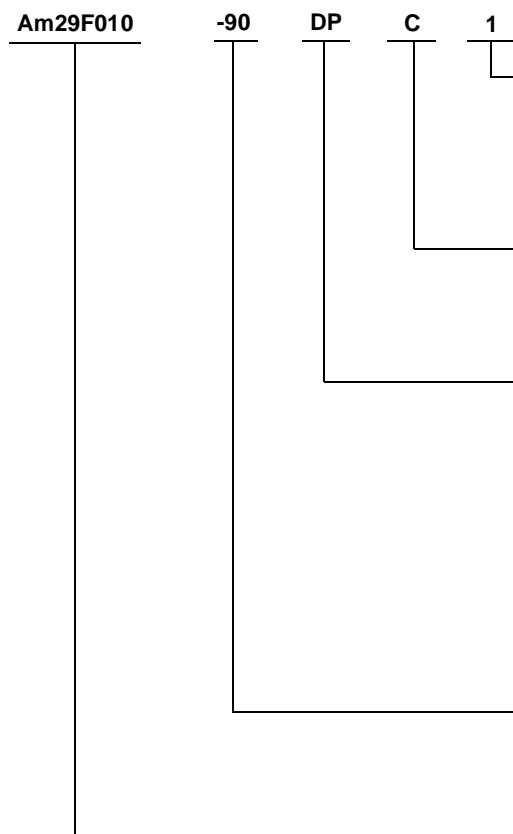
Pad	Signal	Pad Center (mils)		Pad Center (millimeters)	
		X	Y	X	Y
1	V _{CC}	0.00	0.00	0.00	0.00
2	A16	-33.20	-1.30	-0.84	-0.03
3	A15	-41.60	-1.30	-1.06	-0.03
4	A12	-49.90	-1.30	-1.27	-0.03
5	A7	-58.30	-1.30	-1.48	-0.03
6	A6	-66.60	-1.30	-1.69	-0.03
7	A5	-75.00	-1.30	-1.91	-0.03
8	A4	-74.40	-10.50	-1.89	-0.27
9	A3	-75.60	-158.20	-1.92	-4.02
10	A2	-69.40	-166.80	-1.76	-4.24
11	A1	-56.10	-166.80	-1.42	-4.24
12	A0	-46.10	-166.80	-1.17	-4.24
13	D0	-36.30	-166.90	-0.92	-4.24
14	D1	-25.90	-166.90	-0.66	-4.24
15	D2	-13.30	-166.90	-0.34	-4.24
16	V _{SS}	-4.30	-166.90	-0.11	-4.24
17	D3	4.70	-166.90	0.12	-4.24
18	D4	17.30	-166.90	0.44	-4.24
19	D5	27.60	-166.90	0.70	-4.24
20	D6	40.20	-166.90	1.02	-4.24
21	D7	50.60	-166.90	1.29	-4.24
22	CE#	60.60	-166.80	1.54	-4.24
23	A10	74.00	-166.80	1.88	-4.24
24	OE#	81.40	-158.20	2.07	-4.02
25	A11	80.20	-10.40	2.04	-0.26
26	A9	80.80	-1.30	2.05	-0.03
27	A8	72.40	-1.30	1.84	-0.03
28	A13	64.10	-1.30	1.63	-0.03
29	A14	55.70	-1.30	1.41	-0.03
30	WE#	47.40	-1.30	1.20	-0.03

Note: The coordinates above are relative to the center of pad 1 and can be used to operate wire bonding equipment.

ORDERING INFORMATION

Standard Products

AMD KGD products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of the following:



DIE REVISION

This number refers to the specific AMD manufacturing process and product technology reflected in this document. It is entered in the revision field of AMD standard product nomenclature.

TEMPERATURE RANGE

- C = Commercial (0°C to +70°C)
- I = Industrial (-40°C to +85°C)
- E = Extended (-55°C to +125°C)

PACKAGE TYPE AND MINIMUM ORDER QUANTITY

- DP = Waffle Pack
245 die per 5 tray stack
- DG = Gel-Pak[®] Die Tray
486 die per 6 tray stack
- DT = Surftape[™] (Tape and Reel)
2500 per 7-inch reel
- DW = Gel-Pak[®] Wafer Tray (sawn wafer on frame)
Call AMD sales office for minimum order quantity

SPEED OPTION

See Valid Combinations

DEVICE NUMBER/DESCRIPTION

Am29F010 Known Good Die
1 Megabit (128 K x 8-Bit) CMOS Flash Memory—Die Revision 1
5.0 Volt-only Program and Erase

Valid Combinations	
Am29F010-90	DPC 1, DPI 1, DPE 1, DGC 1, DGI 1, DGE 1,
Am29F010-120	DTC 1, DTI 1, DTE 1, DWC 1, DWI 1, DWE 1

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations and to check on newly released combinations.

PRODUCT TEST FLOW

Figure 1 provides an overview of AMD's Known Good Die test flow. For more detailed information, refer to the Am29F010 product qualification database supplement for KGD. AMD implements quality assurance procedures throughout the product test flow. In addition, an

off-line quality monitoring program (QMP) further guarantees AMD quality standards are met on Known Good Die products. These QA procedures also allow AMD to produce KGD products without requiring or implementing burn-in.

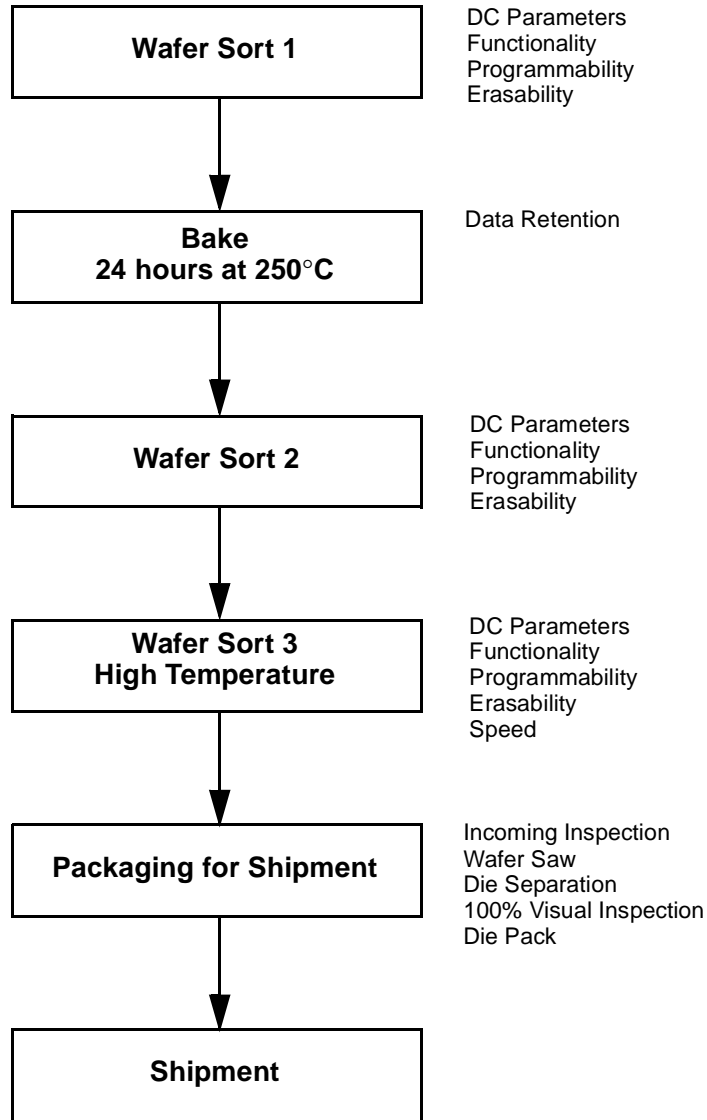


Figure 1. AMD KGD Product Test Flow

PHYSICAL SPECIFICATIONS

Die dimensions	174 mils x 189 mils 4.42 mm x 4.80 mm
Die Thickness	~20 mils or ~0.51 mm
Bond Pad Size	4.47 mils x 4.47 mils 113.48 μm x 113.48 μm
Pad Area Free of Passivation	19.98 mils ² 12,878 μm^2
Pads Per Die	30
Bond Pad Metalization	Al/Si/Cu
Die Backside	No metal, may be grounded (optional)
Passivation	Nitride/SOG/Nitride

DC OPERATING CONDITIONS

V_{CC} (Supply Voltage)	4.5 V to 5.5 V
Junction Temperature Under Bias	T_J (max) = 130°C
For Read-only	T_J (max) = 140°C
Operating Temperature	Commercial 0°C to +70°C Industrial -40°C to +85°C Extended -55°C to +125°C

MANUFACTURING INFORMATION

Manufacturing and Test	Fab 14, Austin, TX
Manufacturing ID	98108AK
Preparation for Shipment	Penang, Malaysia
Fabrication Process	CS19AFDS
Die Revision	1

SPECIAL HANDLING INSTRUCTIONS**Processing**

Do not expose KGD products to ultraviolet light or process them at temperatures greater than 250°C. Failure to adhere to these handling instructions will result in irreparable damage to the devices. For best yield, AMD recommends assembly in a Class 10K clean room with 30% to 60% relative humidity.

Storage

Store at a maximum temperature of 30°C in a nitrogen-purged cabinet or vacuum-sealed bag. Observe all standard ESD handling procedures.

TERMS AND CONDITIONS OF SALE FOR AMD NON-VOLATILE MEMORY DIE

All transactions relating to AMD Products under this agreement shall be subject to AMD's standard terms and conditions of sale, or any revisions thereof, which revisions AMD reserves the right to make at any time and from time to time. In the event of conflict between the provisions of AMD's standard terms and conditions of sale and this agreement, the terms of this agreement shall be controlling.

AMD warrants articles of its manufacture against defective materials or workmanship for a period of ninety (90) days from date of shipment. This warranty does not extend beyond AMD's customer, and does not extend to die which has been affixed onto a board or substrate of any kind. The liability of AMD under this warranty is limited, at AMD's option, solely to repair or to replacement with equivalent articles, or to make an appropriate credit adjustment not to exceed the original sales price, for articles returned to AMD, provided that: (a) The Buyer promptly notifies AMD in writing of each and every defect or nonconformity in any article for which Buyer wishes to make a warranty claim against AMD; (b) Buyer obtains authorization from AMD to return the article; (c) the article is returned to AMD, transportation charges paid by AMD, F.O.B. AMD's factory; and (d) AMD's examination of such article discloses to its satisfaction that such alleged defect or nonconformity actually exists and was not caused by negligence, misuse, improper installation, accident or unauthorized repair or alteration by an entity other than AMD. The aforementioned provisions do not extend the original warranty period of any article which has either been repaired or replaced by AMD.

THIS WARRANTY IS EXPRESSED IN LIEU OF ALL OTHER WARRANTIES, EXPRESSED OR IMPLIED, INCLUDING THE IMPLIED WARRANTY OF FITNESS FOR A PARTICULAR PURPOSE, THE IMPLIED WARRANTY OF MERCHANTABILITY AND OF ALL OTHER OBLIGATIONS OR LIABILITIES ON AMD'S PART, AND IT NEITHER ASSUMES NOR AUTHORIZES ANY OTHER PERSON TO ASSUME FOR AMD ANY OTHER LIABILITIES. THE FOREGOING CONSTITUTES THE BUYERS SOLE AND EXCLUSIVE REMEDY FOR THE FURNISHING OF DEFECTIVE OR NON CONFORMING ARTICLES AND AMD SHALL NOT IN ANY EVENT BE LIABLE FOR DAMAGES BY REASON OF FAILURE OF ANY PRODUCT TO FUNCTION PROPERLY OR FOR ANY SPECIAL, INDIRECT, CONSEQUENTIAL, INCIDENTAL OR EXEMPLARY DAMAGES, INCLUDING BUT NOT LIMITED TO, LOSS OF PROFITS, LOSS OF USE OR COST OF LABOR BY REASON OF THE FACT THAT SUCH ARTICLES SHALL HAVE BEEN DEFECTIVE OR NON CONFORMING.

Buyer agrees that it will make no warranty representations to its customers which exceed those given by AMD to Buyer unless and until Buyer shall agree to indemnify AMD in writing for any claims which exceed AMD's warranty. Buyer assumes all responsibility for successful die prep, die attach and wire bonding processes. Due to the unprotected nature of the AMD Products which are the subject hereof, AMD assumes no responsibility for environmental effects on die.

AMD products are not designed or authorized for use as components in life support appliances, devices or systems where malfunction of a product can reasonably be expected to result in a personal injury. Buyer's use of AMD products for use in life support applications is at Buyer's own risk and Buyer agrees to fully indemnify AMD for any damages resulting in such use or sale.

REVISION SUMMARY FOR AM29F010 KNOWN GOOD DIE

Formatted to match current template. Updated Distinctive Characteristics and General Description sections using the current main data sheet.

Trademarks

Copyright © 1998 Advanced Micro Devices, Inc. All rights reserved.

AMD, the AMD logo, and combinations thereof are registered trademarks of Advanced Micro Devices, Inc.

Product names used in this publication are for identification purposes only and may be trademarks of their respective companies.